

## General Description

The WSD1006GDN22 is the highest performance trench N-Channel MOSFET with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

The WSD1006GDN22 meet the RoHS and Green Product requirement, 100%  $E_{AS}$  guaranteed with full function reliability approved.

## Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent  $CdV/dt$  effect decline
- 100%  $E_{AS}$  Guaranteed
- Green Device Available

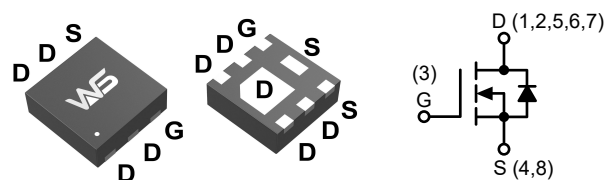
## Product Summary

$BV_{DSS}$	$R_{DS(ON)}$	$I_D$
100V	20m $\Omega$	6.5A

## Applications

- Power Management in TV Converter.
- DC-DC Converter
- LED TV Back Light

## DFN2X2-6L Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	
$I_D@T_C=25^\circ C$	Continuous Drain Current	6.5	A
$I_{DP}$	Pulsed Drain Current	42	
$E_{AS}$	Single Pulse Avalanche Energy	30	mJ
$P_D@T_C=25^\circ C$	Total Power Dissipation	72	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	

## Thermal Data

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	45	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	3.74	

**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$ , Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V$ , $I_D=250\mu A$	100	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V$ , $I_D=6A$	---	20	24	m $\Omega$
		$V_{GS}=4.5V$ , $I_D=5A$	---	24	27	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu A$	1.0	---	2.5	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=80V$ , $V_{GS}=0V$ , $T_J=25^{\circ}\text{C}$	---	---	1.0	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$	---	---	$\pm 100$	nA
$Q_g$	Total Gate Charge	$I_D=6A$ , $V_{DS}=50V$ , $V_{GS}=10V$	---	11	---	nC
$Q_{gs}$	Gate-Source Charge		---	2.0	---	
$Q_{gd}$	Gate-Drain Charge		---	3.0	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{GS}=10V$ , $V_{DS}=50V$ , $R_G=2.2\Omega$ , $I_D=6A$	---	12	---	ns
$T_r$	Rise Time		---	15	---	
$T_{d(off)}$	Turn-Off Delay Time		---	23.5	---	
$T_f$	Fall Time		---	6.2	---	
$C_{iss}$	Input Capacitance	$V_{DS}=50V$ , $V_{GS}=0V$ , $f=1.0\text{MHz}$	---	580	---	pF
$C_{oss}$	Output Capacitance		---	165	---	
$C_{rss}$	Reverse Transfer Capacitance		---	5.1	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	6.5	A
$I_{SP}$	Pulsed Source Current		---	---	42	
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V$ , $I_S=12A$ , $T_J=25^{\circ}\text{C}$	---	---	1.3	V
$t_{rr}$	Reverse Recovery Time	$I_F=12A$ , $dI/dt=100A/\mu s$ , $T_J=25^{\circ}\text{C}$	---	45.2	---	ns
$Q_{rr}$	Reverse Recovery Charge		---	88.1	---	nC

**Note:**

1. Calculated continuous current based on maximum allowable junction temperature.
2. Repetitive rating; pulse width limited by max. junction temperature.
3.  $P_D$  is based on max. junction temperature, using junction-case thermal resistance.
4. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ .
5.  $V_{DD}=50V$ ,  $R_G=25\Omega$ ,  $L=0.3\text{mH}$ , starting  $T_J=25^{\circ}\text{C}$ .

## Typical Characteristics

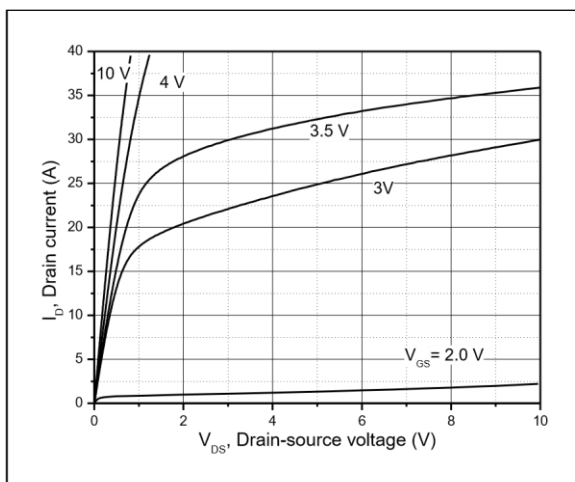


Figure 1, Typ. output characteristics

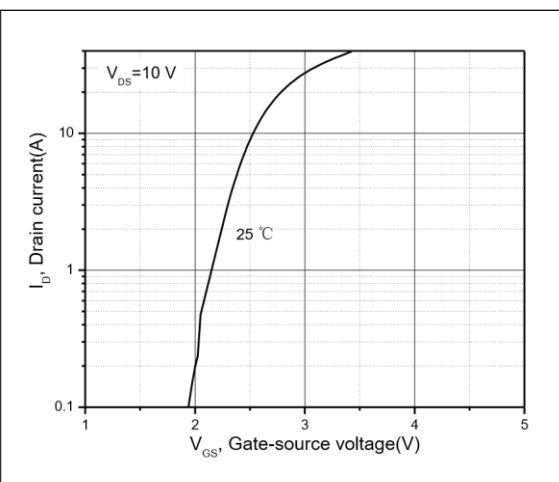


Figure 2, Typ. transfer characteristics

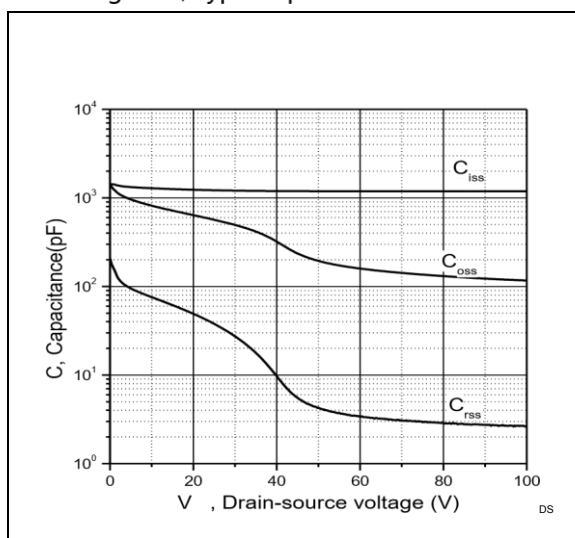


Figure 3, Typ. capacitances

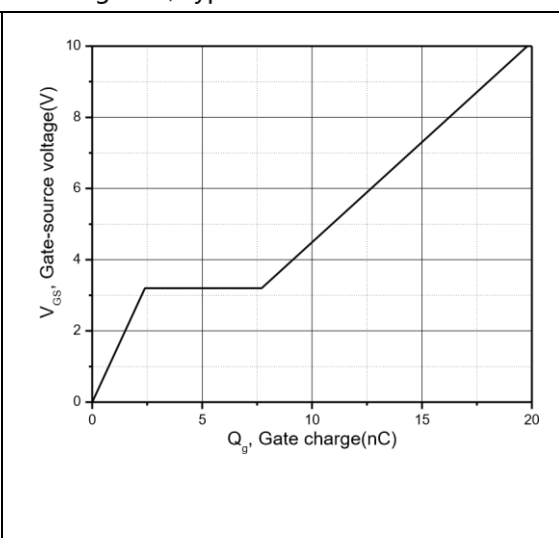


Figure 4, Typ. gate charge

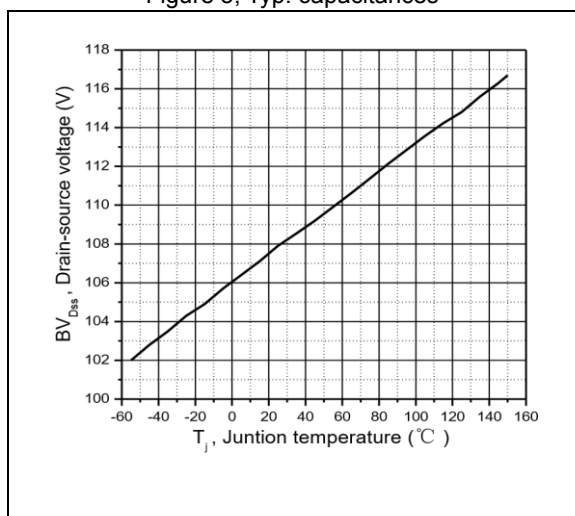


Figure 5, Drain-source breakdown voltage

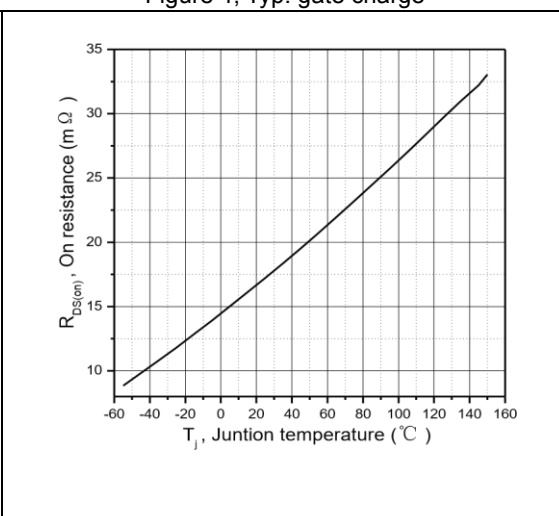


Figure 6, Drain-source on-state resistance

Typical Characteristics (Cont.)

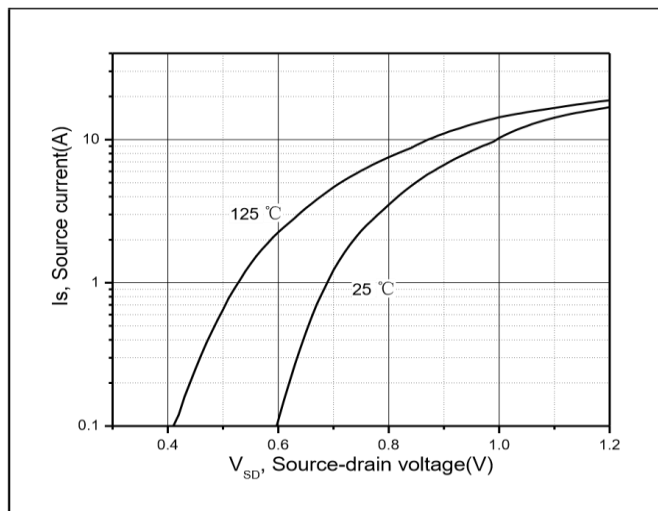


Figure 7, Forward characteristic of body diode

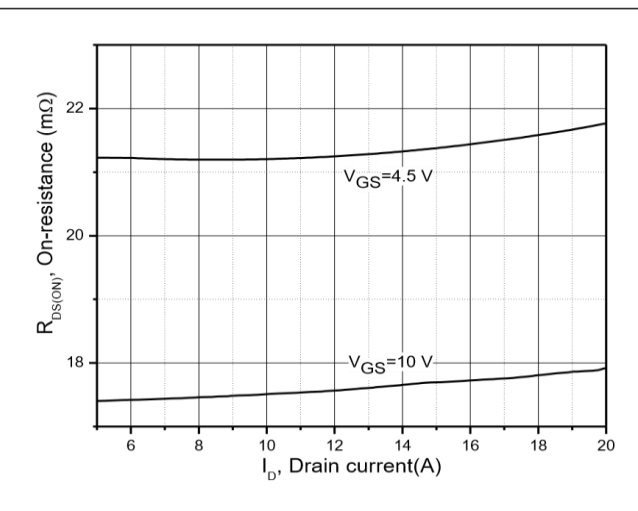


Figure 8, Drain-source on-state resistance

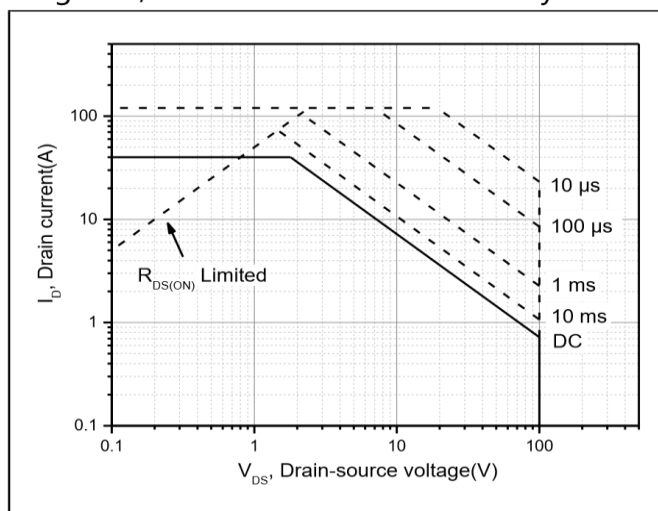
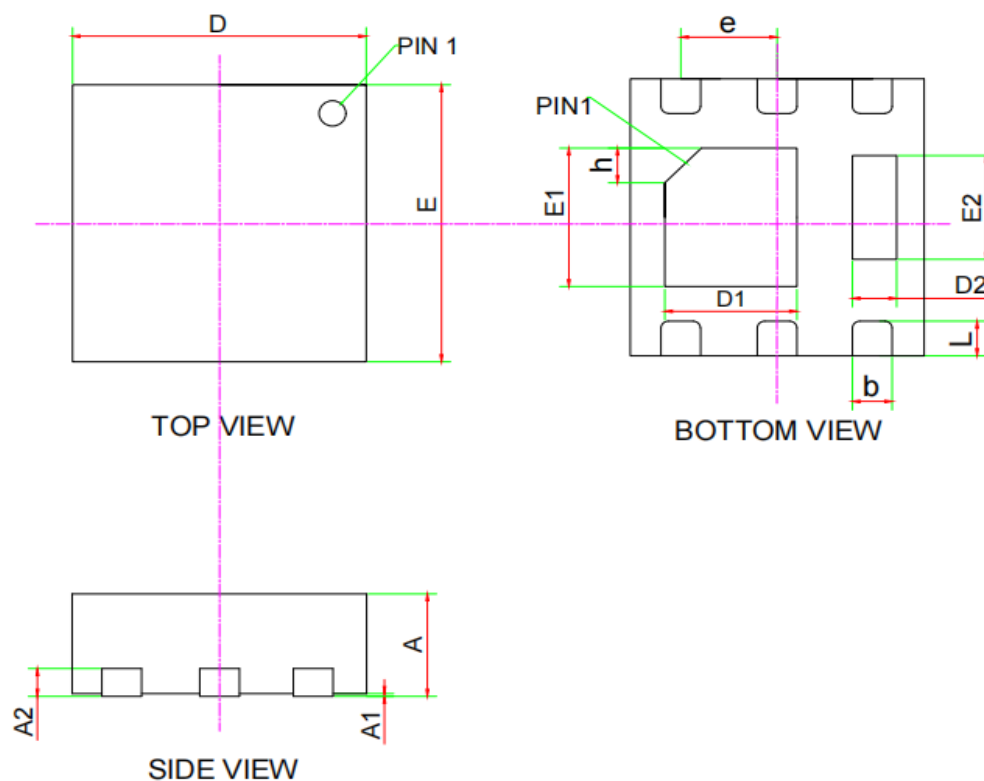


Figure 9, Safe operation area  $T_C = 25\text{ °C}$

Packaging information



SYMBOL	MIN	NOM	MAX
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
A2	0.18	0.20	0.25
b	0.25	0.3	0.35
D	1.95	2.00	2.05
E	1.95	2.00	2.05
D1	0.80	0.90	1.00
E1	0.90	1.00	1.10
D2	0.20	0.30	0.40
E2	0.70	0.80	0.90
L	0.20	0.25	0.30
h	0.15	0.20	0.25
e	0.65 BSC		

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